



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

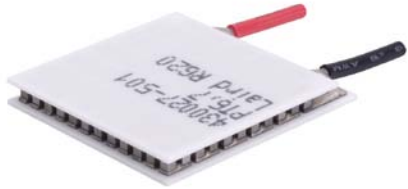
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Thermoelectric Modules



The PolarTEC™ Series consists of porch-style thermoelectric modules (TEMs). The hot side of the ceramic has an extended edge that allows strong lead attachment to accommodate the wiring of multiple TEMs into an array.

This product line is available in 4, 6, and 8 Amp configurations and is ideal for high-volume production. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the PolarTEC Series is designed for higher current and larger heat-pumping applications.

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FEATURES

- Strong lead attachment
- Precise temperature control
- Reliable solid state operation
- No sound or vibration
- DC operation
- RoHS compliant

APPLICATIONS

- Analytical instrumentation
- Photonics laser systems
- Electronic enclosure cooling
- Food & beverage cooling
- Chillers (liquid cooling)
- Consumer appliances

SPECIFICATIONS

| TECHNICAL | | |
|---------------------------|-------|------|
| Hot Side Temperature (°C) | 25°C | 50°C |
| Qmax (Watts) | 29.2` | 33.3 |
| Delta Tmax (°C) | 65 | 75 |
| I _{max} (Amps) | 6.0 | 6.0 |
| V _{max} (Volts) | 8.0 | 9.0 |
| Module Resistance (Ohms) | 1.22 | 1.38 |

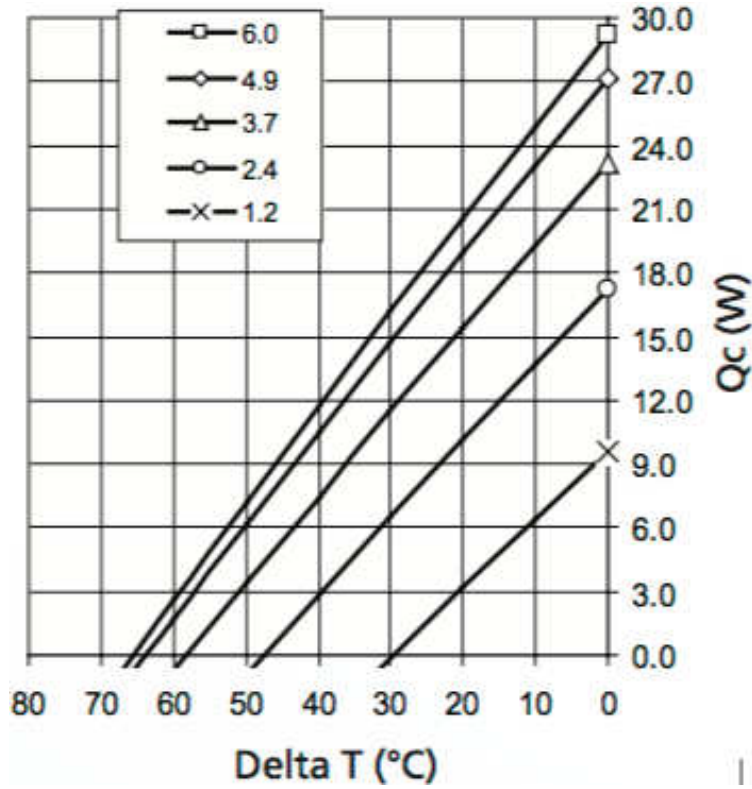
| SUFFIX | THICKNESS (PRIOR TO TINNING) | FLATNESS & PARALLELISM | HOT FACE | COLD FACE | LEAD LENGTH |
|--------|------------------------------|------------------------|----------|-----------|-------------|
| TA | 0.150"±0.001" | 0.001"/0.001" | Lapped | Lapped | 6.0" |
| TB | 0.150"±0.0005" | 0.0005"/0.0005" | Lapped | Lapped | 6.0" |

SEALING OPTIONS

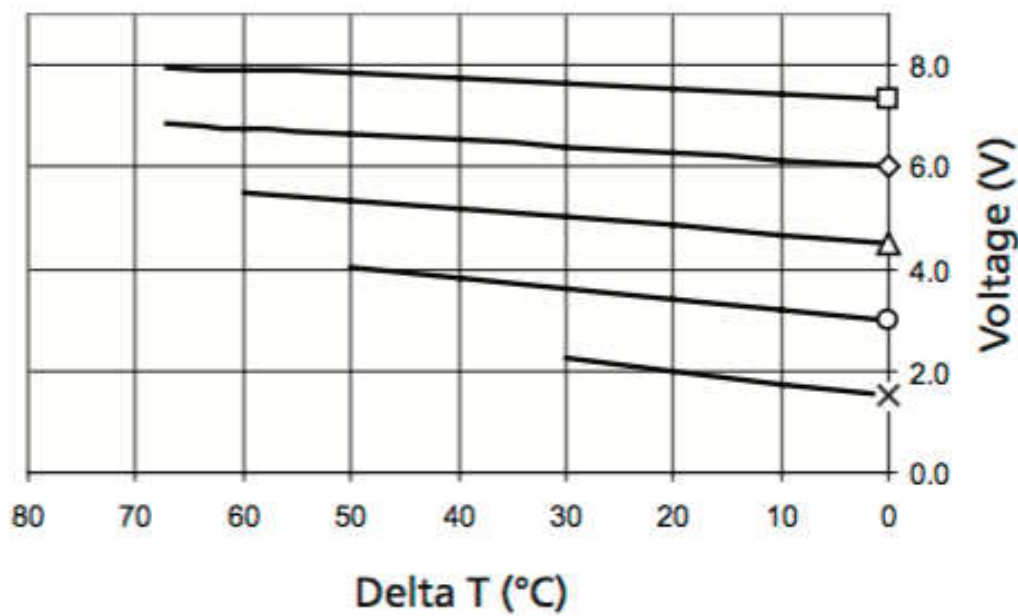
| SUFFIX | SEALANT | COLOR | TEMP RANGE | DESCRIPTION |
|--------|---------|-------|---------------|--|
| RT | RTV | White | -60 to 204 °C | Non-corrosive, silicone adhesive |
| EP | Epoxy | Black | -55 to 150 °C | Low density syntactic foam epoxy encapsulant |

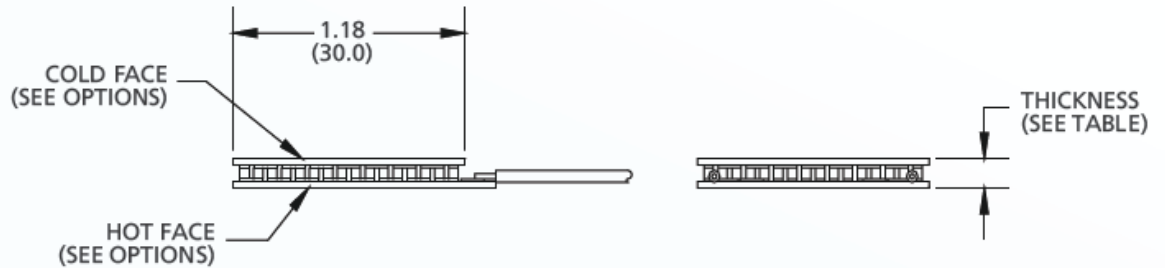
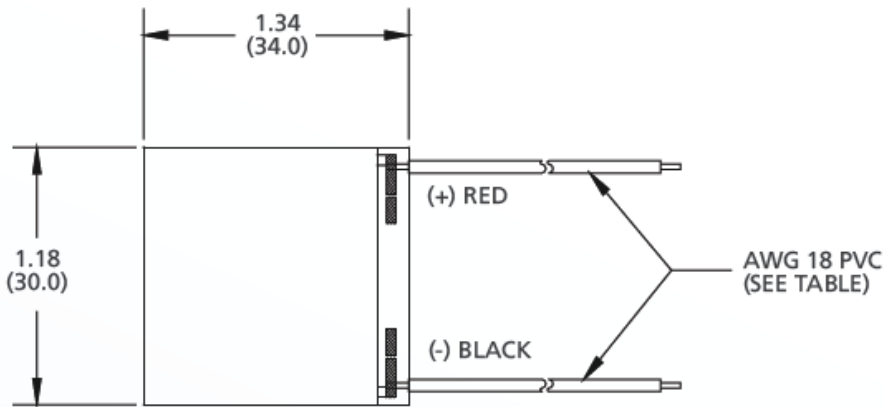
Performance Curves at Th =25°C

THERMO



ELECTRIC





Ceramic Material: Alumina (Al_2O_3)
Solder Construction: 138°C, Bismuth Tin (BiSn)

NOTES

1. Max operating temperature: 80°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation

Laird-ETS-PT6-7-F2-3030-Data-Sheet-101416

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